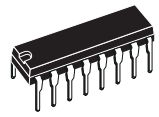
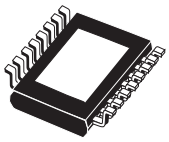
STP08CP05

Low voltage, low current power 8-bit shift register

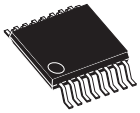
Datasheet - production data



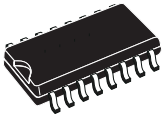
DIP-16



TSSOP16 (Exposed pad)



TSSOP16



SO-16

Features

- Low voltage power supply down to 3 V
- 8 constant current output channels
- Adjustable output current through external resistor
- Serial data IN/parallel data OUT
- 3.3 V micro driver-able
- Output current: 5-100 mA
- 30 MHz clock frequency
- Available in high thermal efficiency TSSOP exposed pad
- ESD protection 2.5 kV HBM, 200 V MM

Description

The STP08CP05 is a monolithic, low voltage, low current, power 8-bit shift register designed for LED panel displays. The STP08CP05 contains an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. In the output stage, eight regulated current sources were designed to provide 5-100 mA constant current to drive the LEDs, the output current setup time is 11 ns (typ), thus improving the system performance.

The STP08CP05 is backward compatible in functionality and footprint with STP8C/L596. Through an external resistor, users can adjust the STP08CP05 output current, controlling in this way the light intensity of LEDs, in addition, user can adjust LED's brightness intensity from 0% to 100% via $\overline{OE}$ pin.

The STP08CP05 guarantees a 20 V output driving capability, allowing users to connect more LEDs in series. The high clock frequency, 30 MHz, also satisfies the system requirement of high volume data transmission. The 3.3 V of voltage supply is useful for applications that interface with any micro from 3.3 V. Compared with a standard TSSOP package, the TSSOP exposed pad increases heat dissipation capability by a 2.5 factor.

Table 1. Device summary

Order codes	Package	Packaging
STP08CP05B1R	DIP-16	25 parts per tube
STP08CP05MTR	SO-16 (Tape and reel)	2500 parts per reel
STP08CP05TTR	TSSOP16 (Tape and reel)	2500 parts per reel
STP08CP05XTTR	TSSOP16 exposed-pad (Tape and reel)	2500 parts per reel

Contents

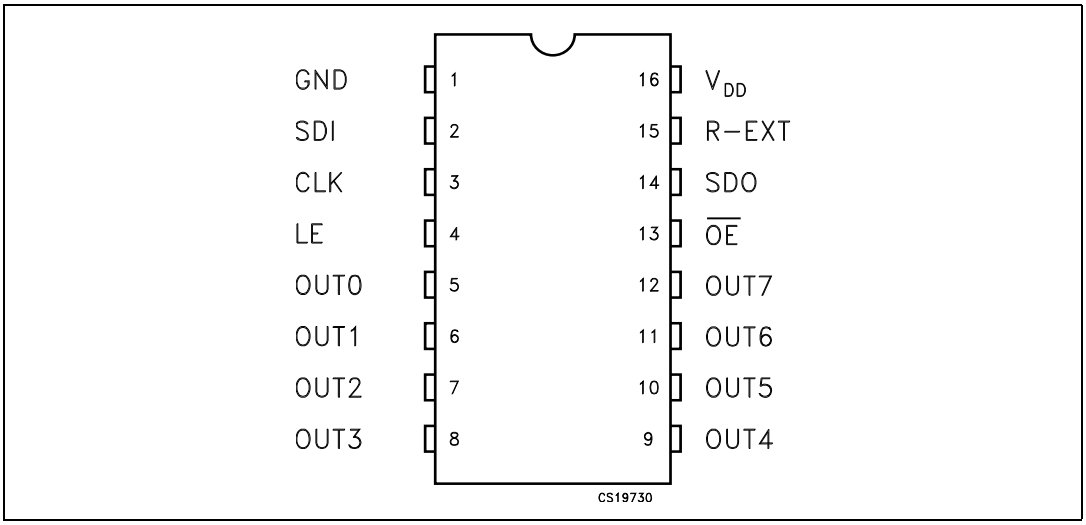
1 Summary description

Table 2. Typical current accuracy

Output voltage	Current accuracy		Output current
	Between bits	Between ICs	
≥ 1.3 V	± 1.5%	± 3%	20 to 100 mA

1.1 Pin connection and description

Figure 1. Connections diagram



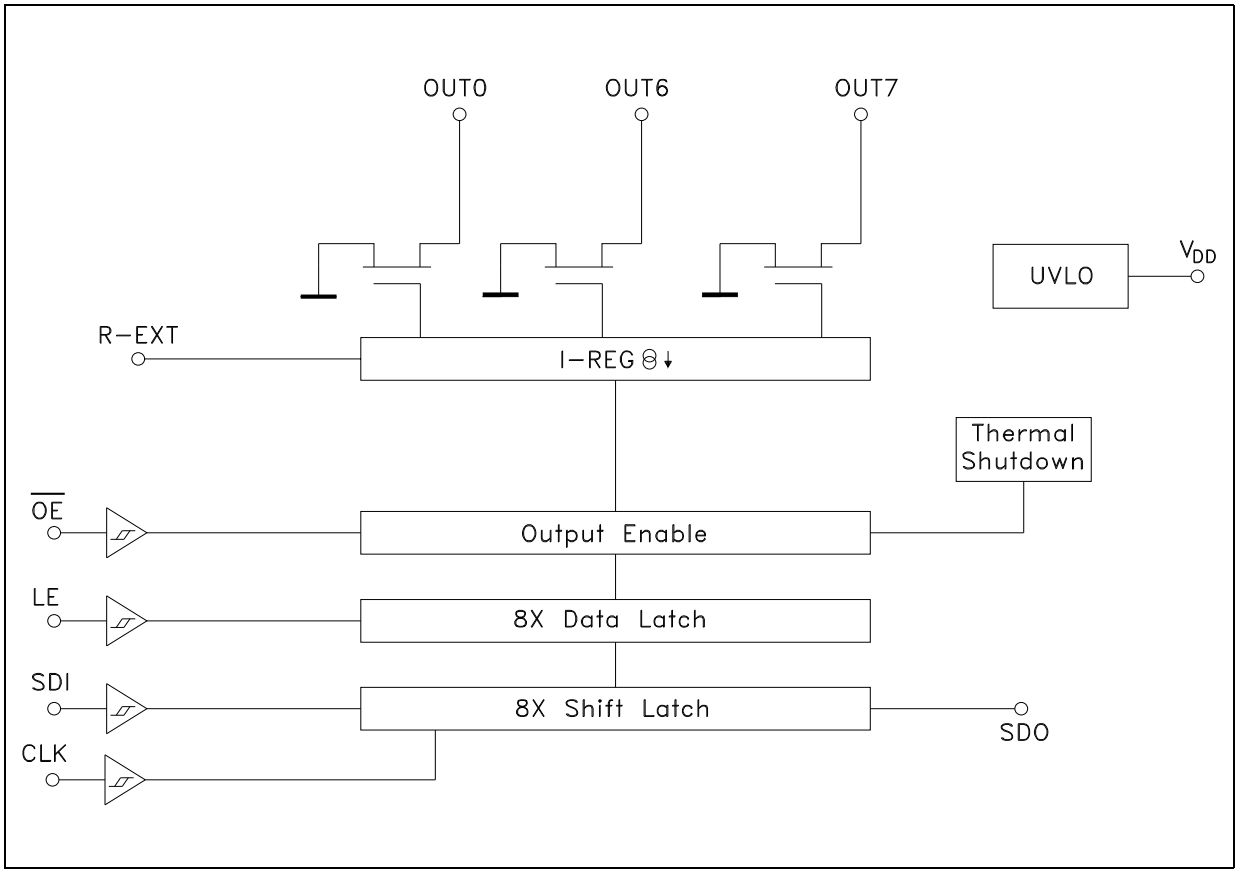
Note: The exposed pad should be electrically connected to a metal land electrically isolated or connected to ground.

Table 3. Pin description

Pin N°	Symbol	Name and function
1	GND	Ground terminal
2	SDI	Serial data input terminal
3	CLK	Clock input terminal
4	LE	Latch input terminal
5-12	OUT 0-7	Output terminal
13	$\overline{OE}$	Output enable input terminal (active low)
14	SDO	Serial data out terminal
15	R-EXT	Constant current programming
16	V_{DD}	5 V supply voltage terminal

2 Block diagram

Figure 2. Block diagram



3 Maximum rating

Stressing the device above the rating listed in the “absolute maximum ratings” table may cause permanent damage to the device. these are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

3.1 Absolute maximum ratings

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DD}	Supply voltage I_{GND}	0 to 7	V
V_O	Output voltage	-0.5 to 20	V
I_O	Output current	100	mA
I_{GND}	GND terminal current	800	mA
f_{CLK}	Clock frequency	50	MHz
T_{OPR}	Operating temperature range	-40 to +125	°C
T_{STG}	Storage temperature range	-55 to +150	°C

3.2 Thermal data

Table 5. Thermal data

Symbol	Parameter	DIP-16	SO-16	TSSOP-16	TSSOP-16 (1) (exposed pad)	Unit
R_{thJA}	Thermal resistance junction-ambient	90	125	140	37.5	°C/W

1. The exposed-pad should be soldered to the PBC to realize the thermal benefits

3.3 Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V_{DD}	Supply voltage		3.0		5.5	V
V_O	Output voltage				20	V
I_O	Output current	OUTn	5		100	mA
I_{OH}	Output current	SERIAL-OUT			+1	mA
I_{OL}	Output current	SERIAL-OUT			-1	mA
V_{IH}	Input voltage		0.7 V_{DD}		V_{DD}+0.3	V
V_{IL}	Input voltage		-0.3		0.3 V_{DD}	V
t_{wLAT}	LE pulse width	V_{DD} = 3.0 to 5.0 V	20			ns
t_{wCLK}	CLK pulse width		20			ns
t_{wEN}	$\overline{OE}$ pulse width		200			ns
$t_{SETUP(D)}$	Setup time for DATA		7			ns
$t_{HOLD(D)}$	Hold time for DATA		4			ns
$t_{SETUP(L)}$	Setup time for LATCH		15			ns
f_{CLK}	Clock frequency	Cascade operation (1)			30	MHz

1. In order to achieve high cascade data transfer, please consider t_r/t_f timings carefully.

4 Electrical characteristics

V_{DD} = 3.3 V to 5 V, T = 25 °C, unless otherwise specified.

Table 7. Electrical characteristics

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V_{IH}	Input voltage high level		0.7 V_{DD}		V_{DD}	V
V_{IL}	Input voltage low level		GND		0.3V_{DD}	V
I_{OH}	Output leakage current	V_{OH} = 20 V		0.5	10	µA
V_{OL}	Output voltage (Serial-OUT)	I_{OL} = 1 mA		0.03	0.4	V
V_{OH}	Output voltage (Serial-OUT)	I_{OH} = -1 mA	V_{OH} - V_{DD} =- 0.4 V			V
I_{OL1}	Output current	V_O = 0.3 V, R_{ext} = 3.9 kΩ	4.25	5	5.75	mA
I_{OL2}		V_O = 0.3 V, R_{ext} = 970 Ω	19.4	20	20.6	
I_{OL3}		V_O = 1.3 V, R_{ext} = 190 Ω	97	100	103	
ΔI_{OL1}	Output current error between bit (All Output ON)	V_O = 0.3 VR_{EXT} = 3.9 kΩ		± 5	± 8	%
ΔI_{OL2}		V_O = 0.3 VR_{EXT} = 970 Ω		± 1.5	± 2.75	
ΔI_{OL3}		V_O = 1.3 VR_{EXT} =190 Ω		± 1.2	± 2.5	
$R_{SIN(up)}$	Pull-up resistor		150	300	600	KΩ
$R_{SIN(down)}$	Pull-down resistor		100	200	400	KΩ
$I_{DD(OFF1)}$	Supply current (OFF)	R_{EXT} = 980 OUT 0 to 7 = OFF		4	5	mA
$I_{DD(OFF2)}$		R_{EXT} = 250 OUT 0 to 7 = OFF		11.2	13.5	
$I_{DD(ON1)}$	Supply current (ON)	R_{EXT} = 980 OUT 0 to 7 = ON		4.5	5	
$I_{DD(ON2)}$		R_{EXT} = 250 OUT 0 to 7 = ON		11.7	13.5	
Thermal	Thermal protection (1)			170		°C

1. Guaranteed by design (not tested)
The thermal protection switches OFF only the outputs

5 Switching characteristics

V_{DD} = 5 V, T = 25 °C, unless otherwise specified.

Table 8. Switching characteristics

Symbol	Parameter	Test conditions			Min	Typ	Max	Unit
t_{PLH1}	Propagation delay time, CLK-OUTn, LE = H, OE = L	V_{DD} = 3.3 V V_{IL} = GND I_O = 20 mA R_{EXT} = 1 KΩ	V_{IH} = V_{DD} C_L = 10 pF V_L = 3.0 V R_L = 60 Ω	V_{DD} = 3.3 V		35	50	ns
				V_{DD} = 5 V		18	28	
t_{PLH2}	Propagation delay time, LE -OUTn, OE = L			V_{DD} = 3.3 V		48	74	ns
				V_{DD} = 5 V		30	50	
t_{PLH3}	Propagation delay time, OE -OUTn, LE = H			V_{DD} = 3.3 V		55	82	ns
				V_{DD} = 5 V		37	58	
t_{PLH}	Propagation delay time, CLK-SDO			V_{DD} = 3.3 V		21	28	ns
				V_{DD} = 5 V		17	22	
t_{PHL1}	Propagation delay time, CLK-OUTn, LE = H, OE = L			V_{DD} = 3.3 V		11	17	ns
				V_{DD} = 5 V		7	11	
t_{PHL2}	Propagation delay time, LE -OUTn, OE = L			V_{DD} = 3.3 V		24	40	ns
				V_{DD} = 5 V		21	31	
t_{PHL3}	Propagation delay time, OE -OUTn, LE = H			V_{DD} = 3.3 V		20	35	ns
				V_{DD} = 5 V		18	28	
t_{PHL}	Propagation delay time, CLK-SDO			V_{DD} = 3.3 V		24	32	ns
				V_{DD} = 5 V		19	25	
t_{ON}	Output rise time 10~90% of voltage waveform			V_{DD} = 3.3 V		26	40	ns
				V_{DD} = 5 V		11	17	
t_{OFF}	Output fall time 90~10% of voltage waveform			V_{DD} = 3.3 V		5	10	ns
				V_{DD} = 5 V		4	8	
t_r	CLK rise time (1)						5000	ns
t_f	CLK fall time (1)						5000	ns

1. In order to achieve high cascade data transfer, please consider tr/tf timings carefully.

6 Equivalent circuit and outputs

Figure 3. $\overline{OE}$ terminal

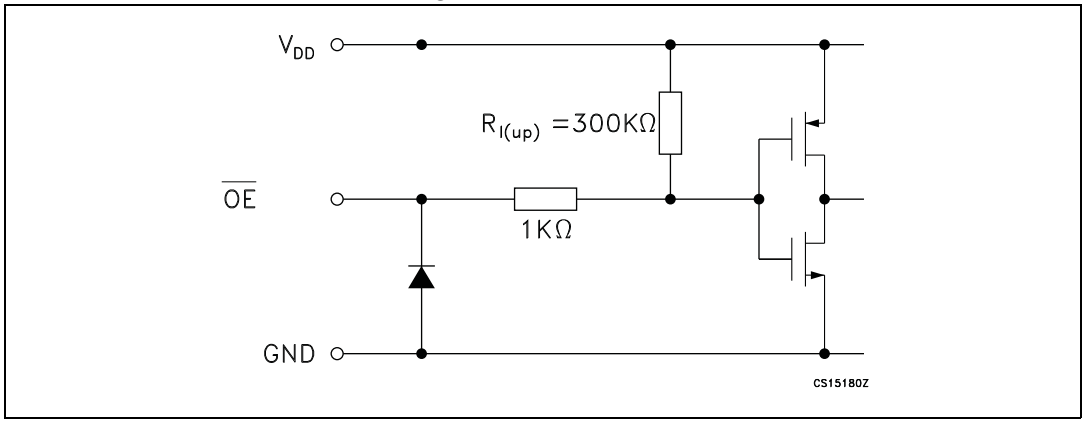


Figure 4. LE terminal

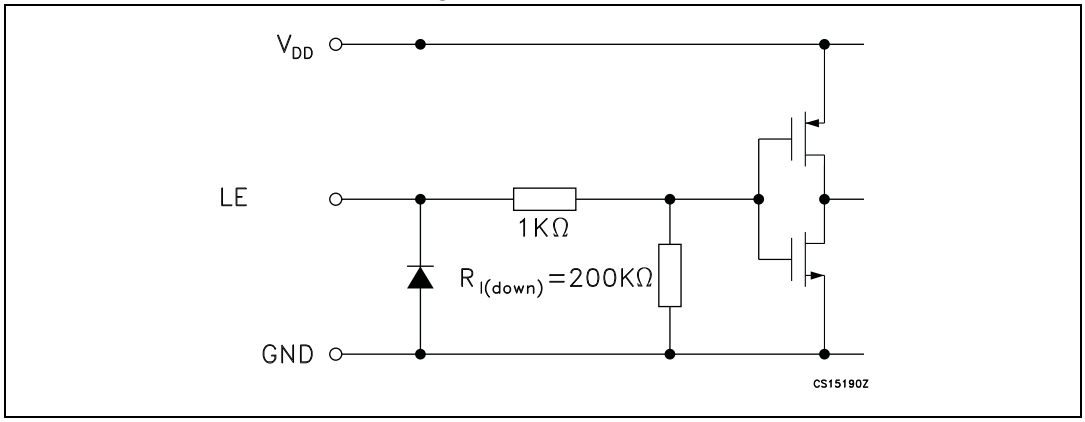


Figure 5. CLK, SDI terminal

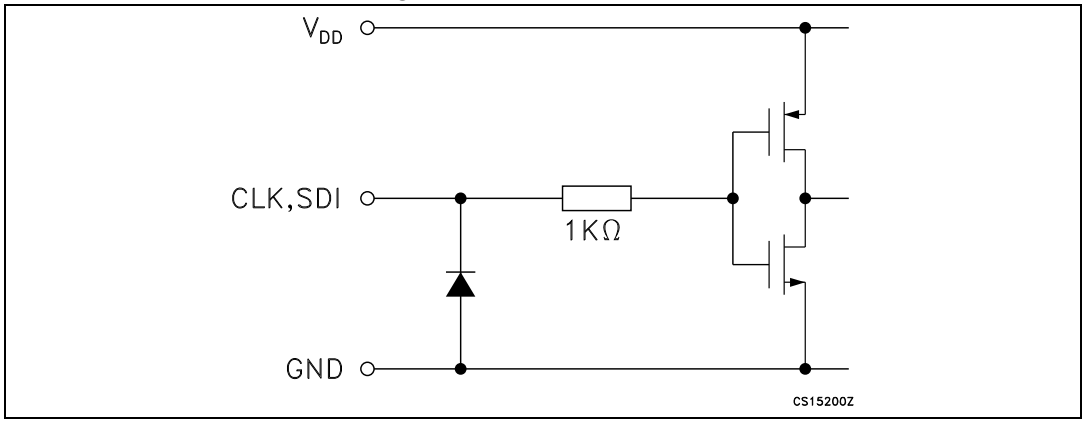
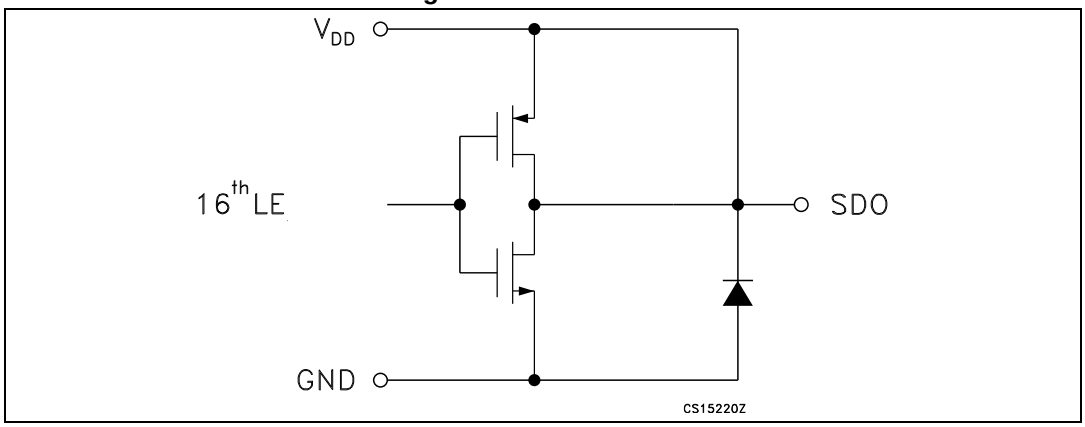


Figure 6. SDO terminal



7 Truth table and timing diagram

7.1 Truth table

Table 9. Truth table

Clock	$\overline{LE}$	$\overline{OE}$	SDI	$\overline{OUT0}$ ..... $\overline{OUT0}$ ..... $\overline{OUT7}$	SDO
↑	H	L	Dn	Dn ..... Dn -5 ..... Dn -7	Dn -7
↑	L	L	Dn + 1	No change	Dn -7
↑	H	L	Dn + 2	$\overline{Dn+2}$ ..... $\overline{Dn-3}$ ..... $\overline{Dn-5}$	Dn -5
↓	X	L	Dn + 3	$\overline{Dn+2}$ ..... $\overline{Dn-3}$ ..... $\overline{Dn-5}$	Dn -5
↓	X	H	Dn + 3	OFF	Dn -5

Note: OUT0 to OUT7 = ON when Dn = H; OUT0 to OUT7 = OFF when Dn = L.

7.2 Timing diagram

Figure 7. Timing diagram

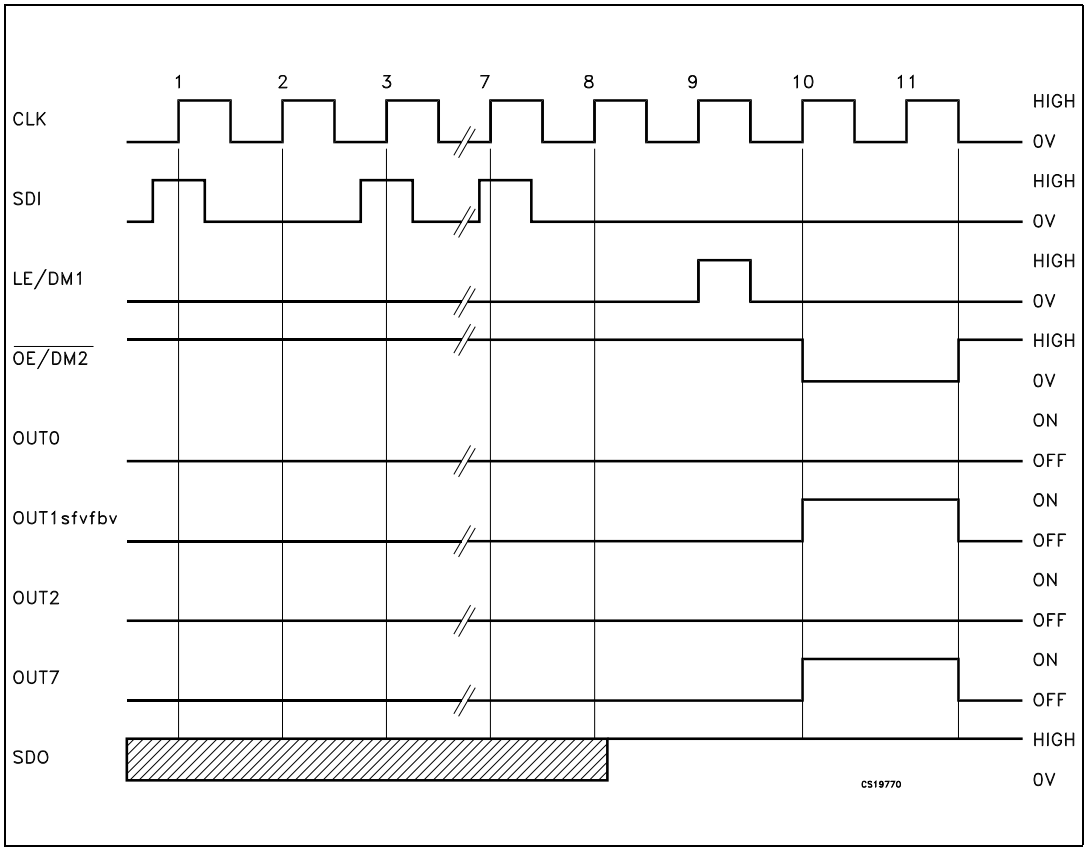


Figure 8. Clock, serial-in, serial-out

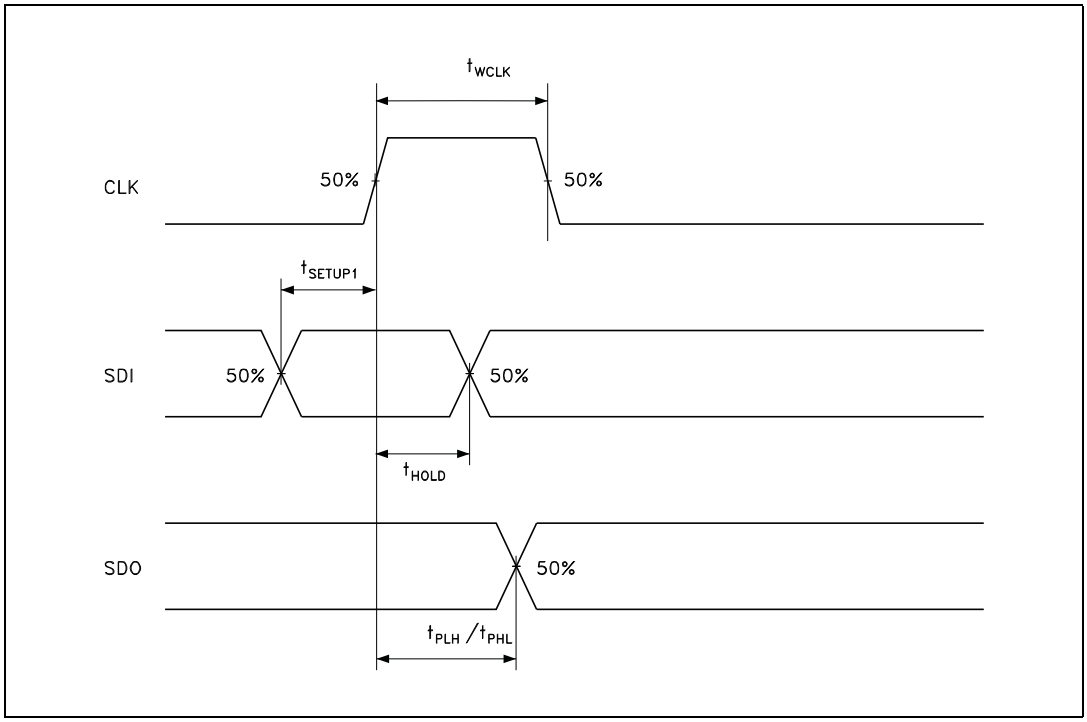


Figure 9. Clock, serial-in, latch, enable, outputs

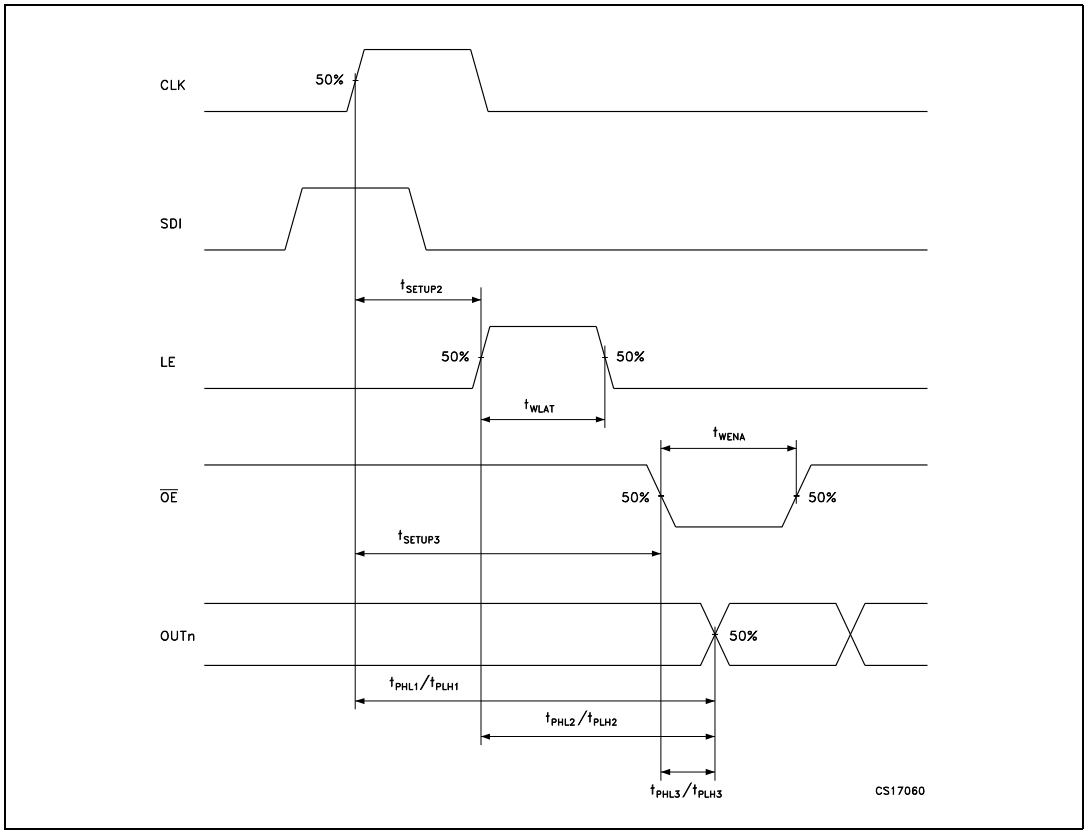
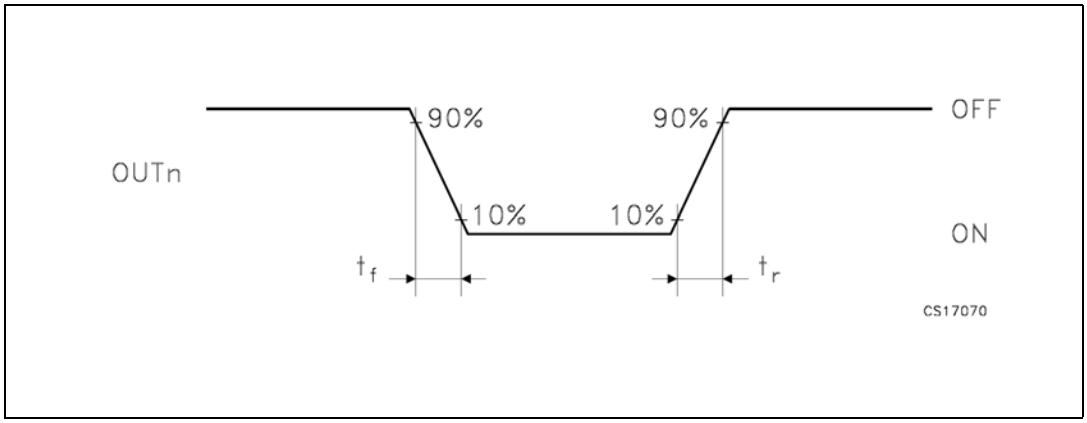
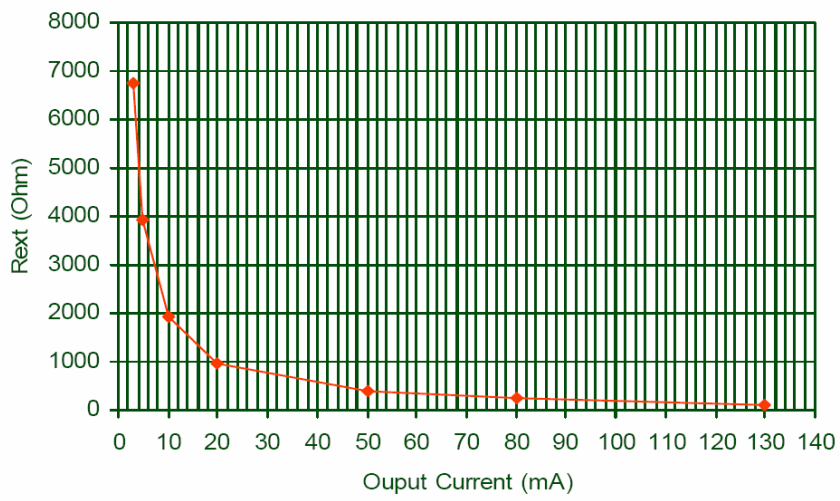


Figure 10. Outputs



8 Typical characteristics

Figure 11. Output current-R_{EXT} resistor



T_A = 25 °C, Iset = 3 mA; 5 mA; 10 mA; 20 mA; 50 mA; 80 mA; Max

Table 10. Output current-R_{EXT} resistor

Output current (mA)	3	5	10	20	50	80	130
Rext (Ω)	6740	3930	1913	963	386	241	124

Note: Maximum output current capabilities setting was 130 mA applying an Rext = 124 Ω

Figure 12. I_{SET} vs drop out voltage (V_{DROP})

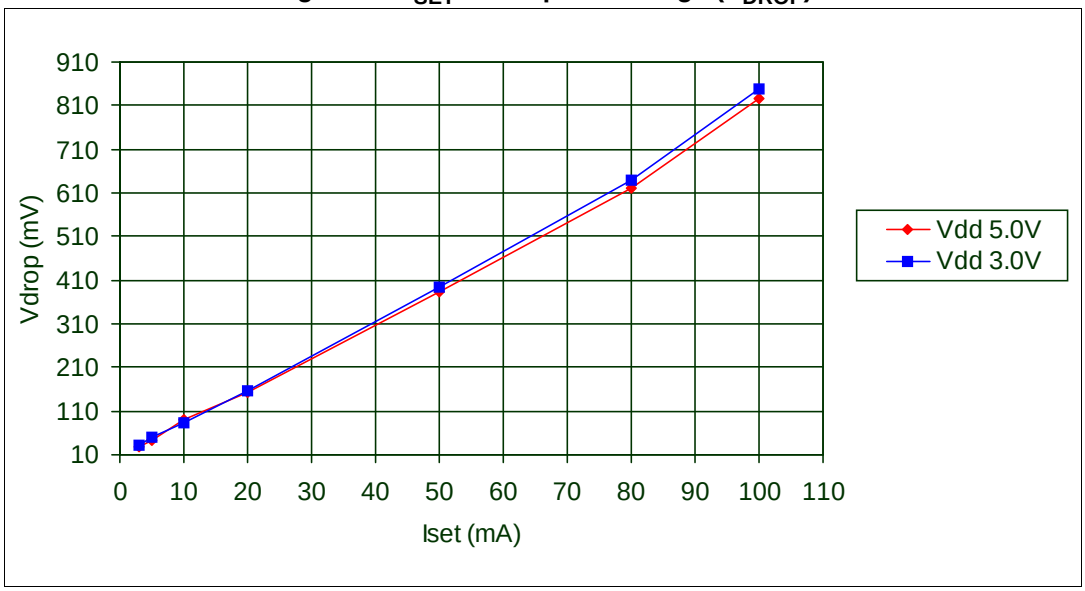
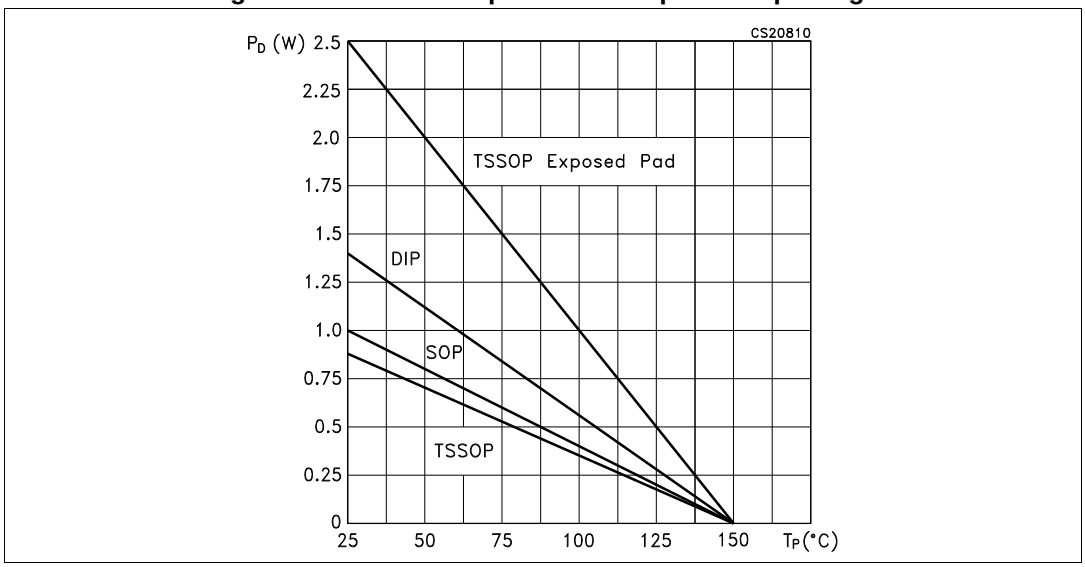


Table 11. I_{SET} vs drop out voltage (V_{DROP})

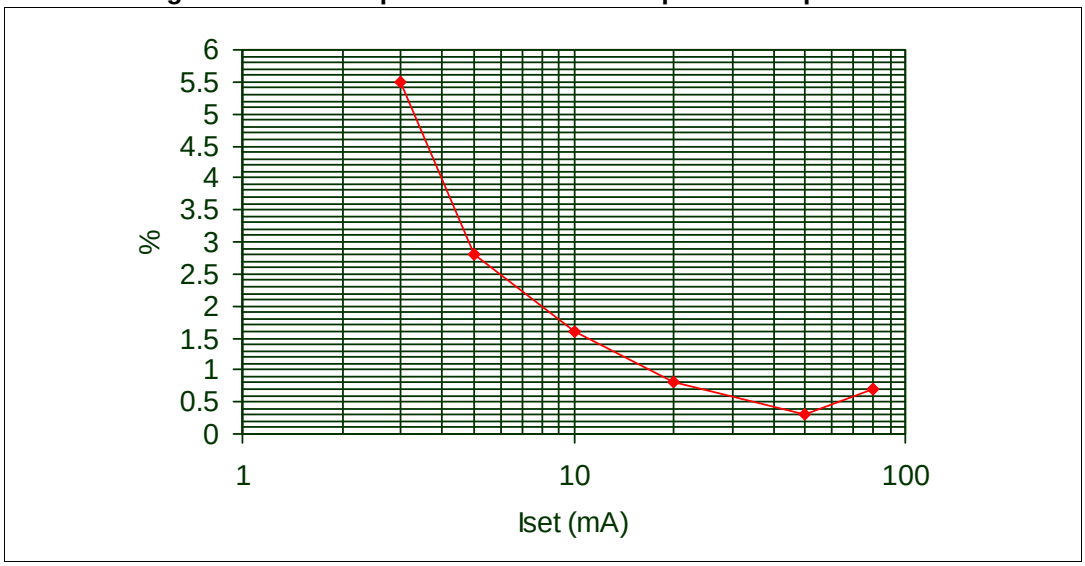
Vdd (V)	I set (mA)	Rext (Ω)	Vdrop min (mV)	Vdrop max (mV)	Vdrop AVG (mV)
3	3	6470	30.6	31.2	30.93
	5	3930	46.5	52.9	48.63
	10	1910	80.9	100	82.26
	20	963	150	161	157
	50	386	392	396	394.3
	80	241	636	646	640.3
	100	192	846	850	848
5	3	6470	25.6	29	26.96
	5	3930	40.8	41.7	41.16
	10	1910	80.1	105	89.2
	20	963	153	154	154
	50	386	379	386	382
	80	241	618	626	621
	100	192	825	830	827

Figure 13. Power dissipation vs temperature package



Note: The exposed-pad should be soldered to the PBC to realize the thermal benefits.

Figure 14. Current precision between outputs vs output current



9 Test circuit

Figure 15. DC characteristics

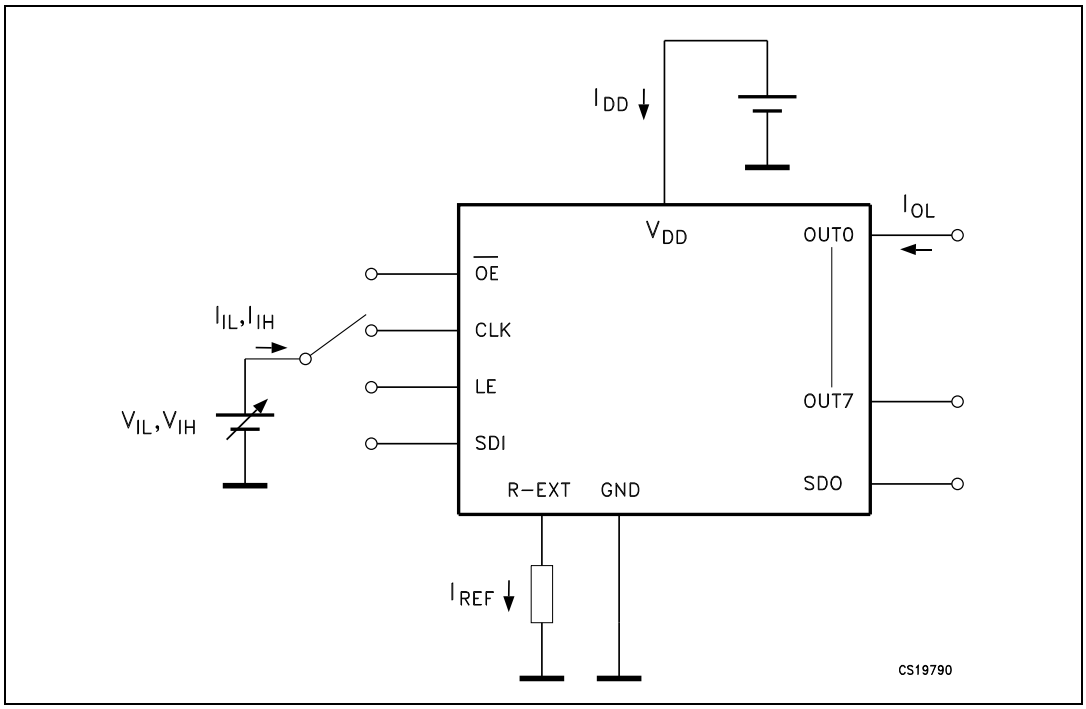


Figure 16. AC characteristics

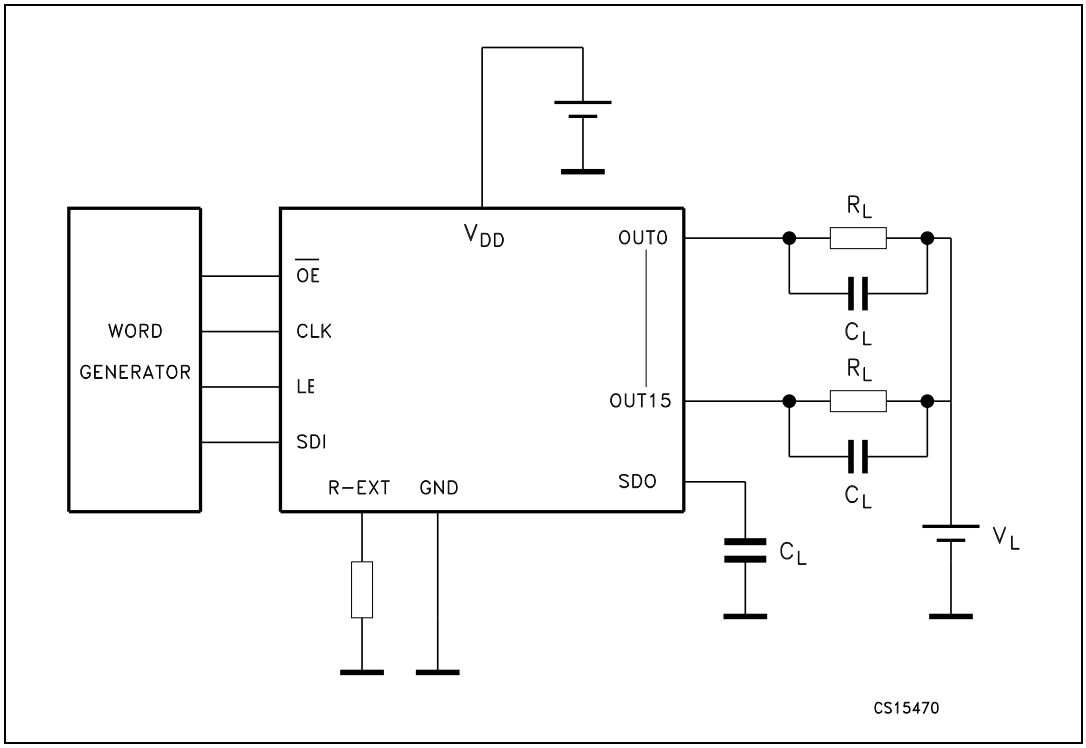
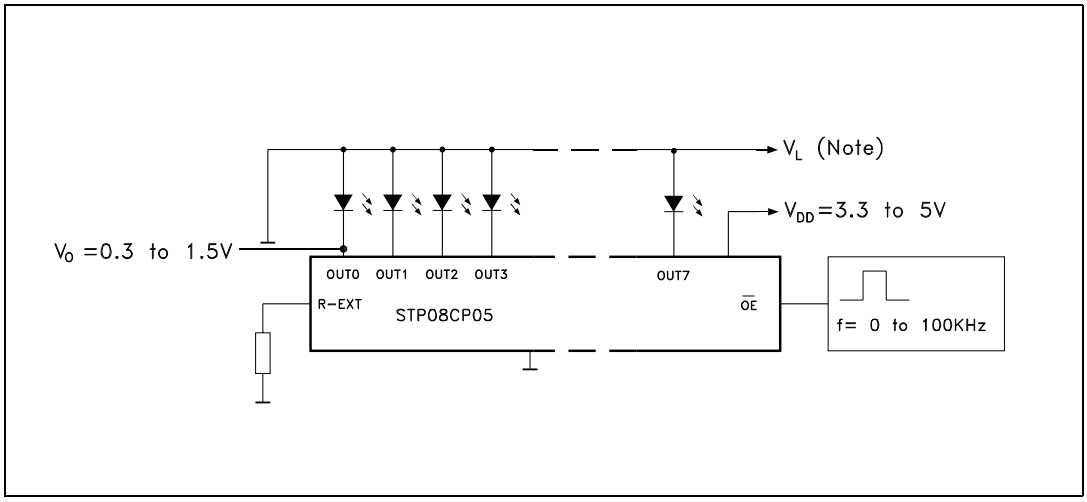


Figure 17. Typical application schematic



10 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK® is an ST trademark.

Table 12. DIP16 mechanical data

Dim	mm		
	Min	Typ	Max
a1	0.51		
B	0.77		1.65
b		0.5	
b1		0.25	
D			20
E		8.5	
e		2.54	
e3		17.78	
F			7.1
I			5.1
L		3.3	
Z			1.27

Figure 18. DIP16 drawing

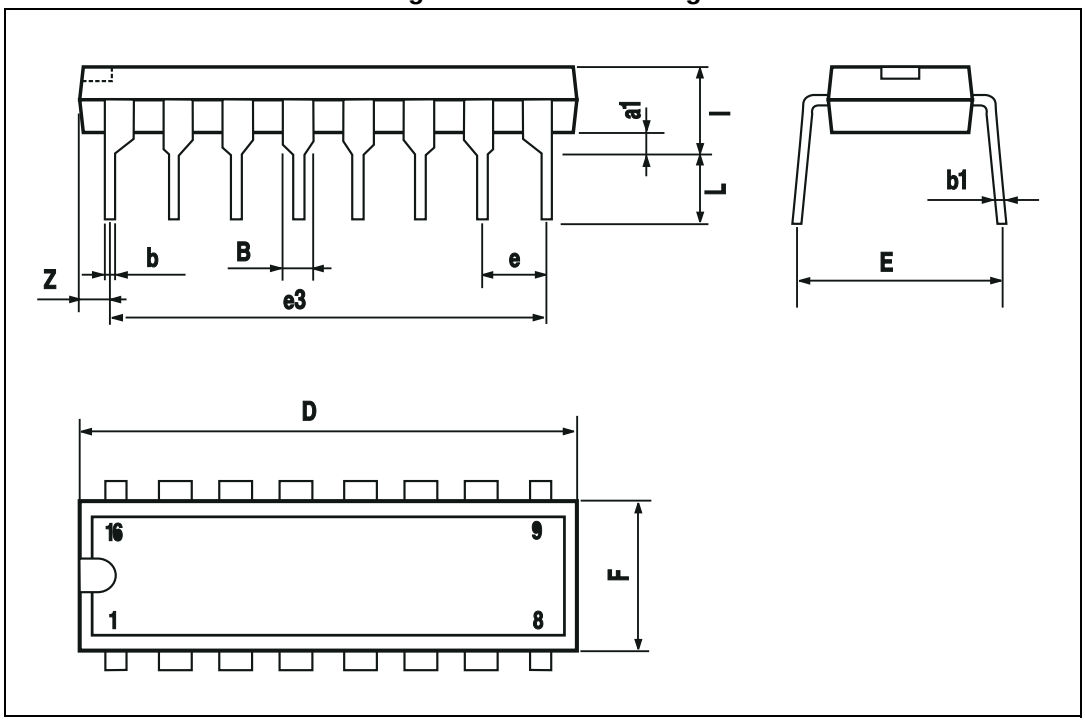


Table 13. HTSSOP16 exposed pad mechanical data

Dim	mm		
	Min	Typ	Max
A			1.20
A1			0.15
A2	0.80	1.00	1.05
b	0.19		0.30
c	0.09		0.20
D	4.90	5.00	5.10
D1	2.8	3	3.2
E	6.20	6.40	6.60
E1	4.30	4.40	4.50
E2	2.8	3	3.2
e		0.65	
L	0.45	0.60	0.75
L1		1.00	
k	0.00		8.00
aaa			0.10

Figure 19. HTSSOP16 exposed pad drawing

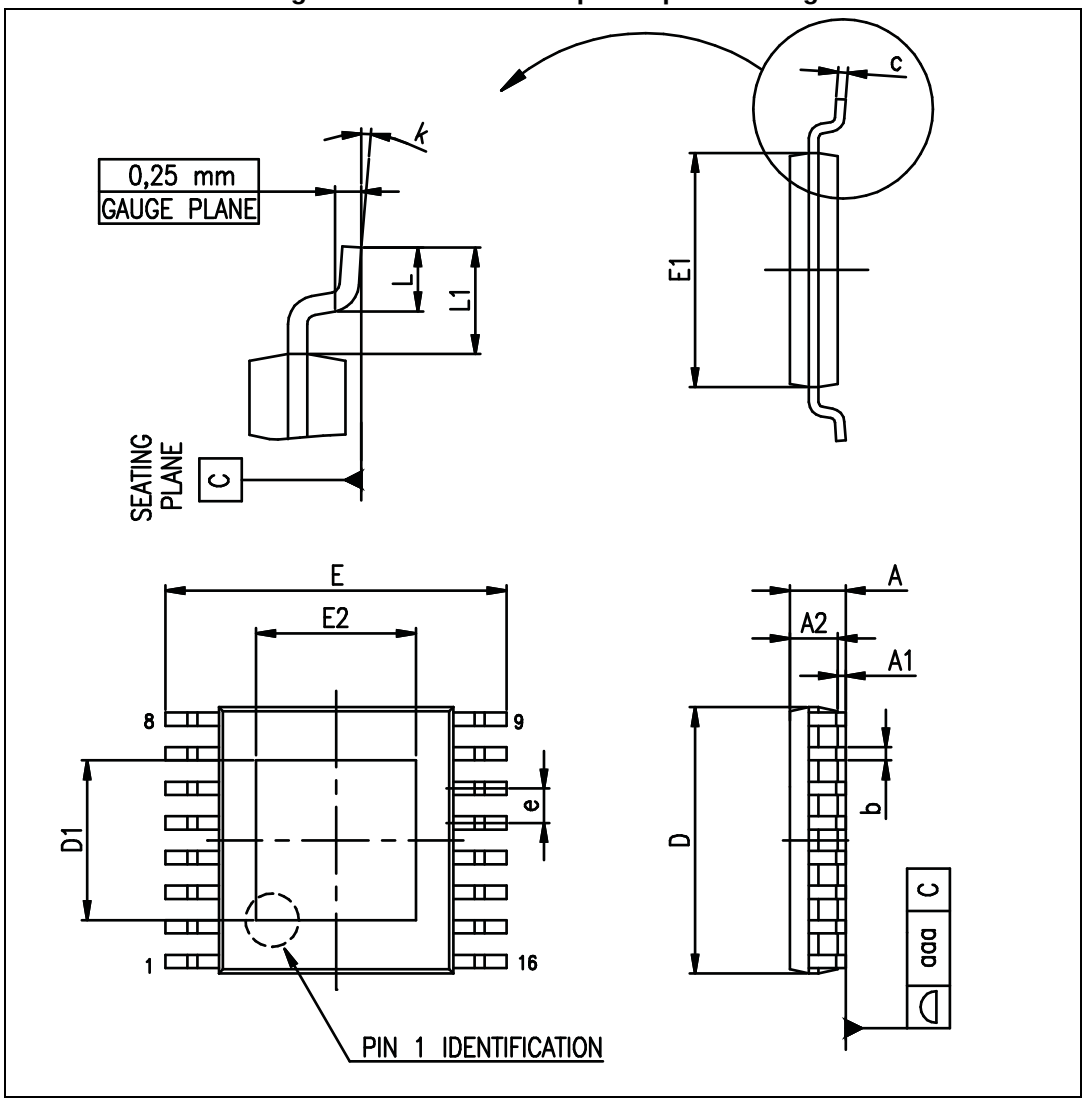


Table 14. HTSSOP16 mechanical data

Dim	mm		
	Min	Typ	Max
A			1.20
A1			0.15
A2	0.80	1.00	1.05
b	0.19		0.30
c	0.09		0.20
D	4.90	5.00	5.10
D1	2.8	3	3.2
E	6.20	6.40	6.60
E1	4.30	4.40	4.50
E2	2.8	3	3.2
e		0.65	
L	0.45	0.60	0.75
L1		1.00	
k	0.00		8.00
aaa			0.10

Figure 20. HTSSOP16 mechanical drawing

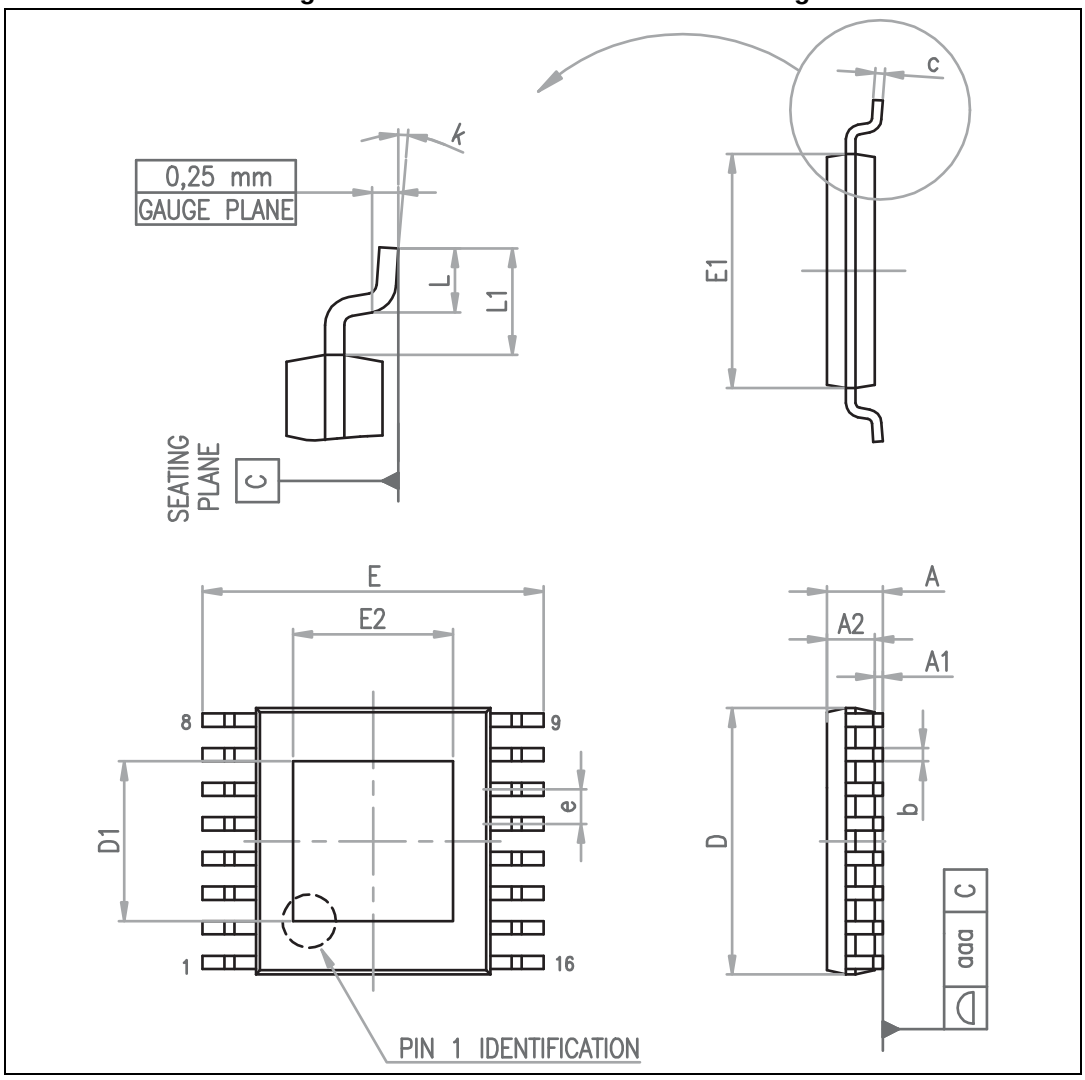


Table 15. SO16N dimensions

Dim	mm		
	Min	Typ	Max
A			1.75
A1	0.10		0.25
A2	1.25		
b	0.31		0.51
c	0.17		0.25
D	9.80	9.90	10.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e		1.27	
h	0.25		0.50
L	0.40		1.27
k	0		8°
ccc			0.10

Figure 21. Package drawing

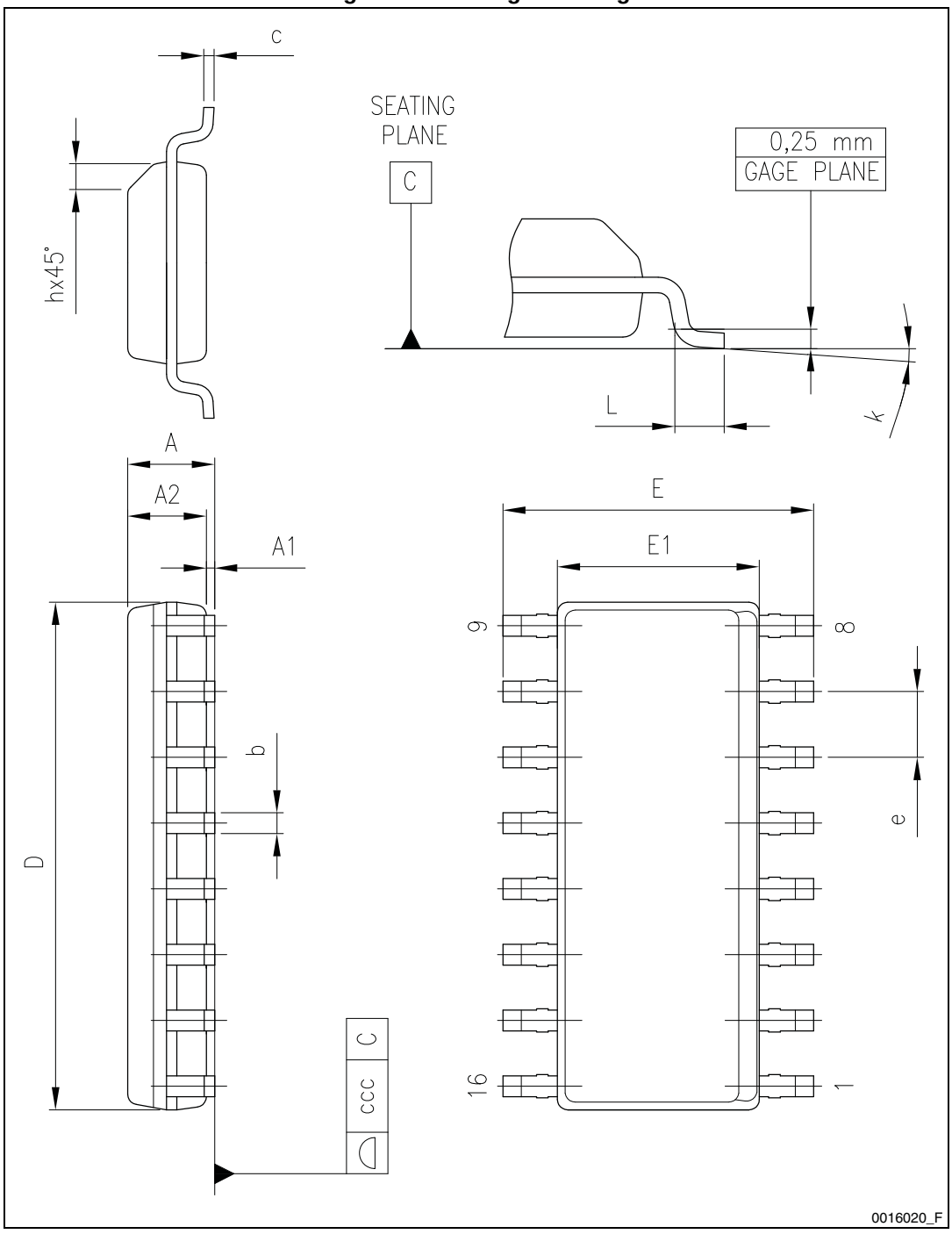
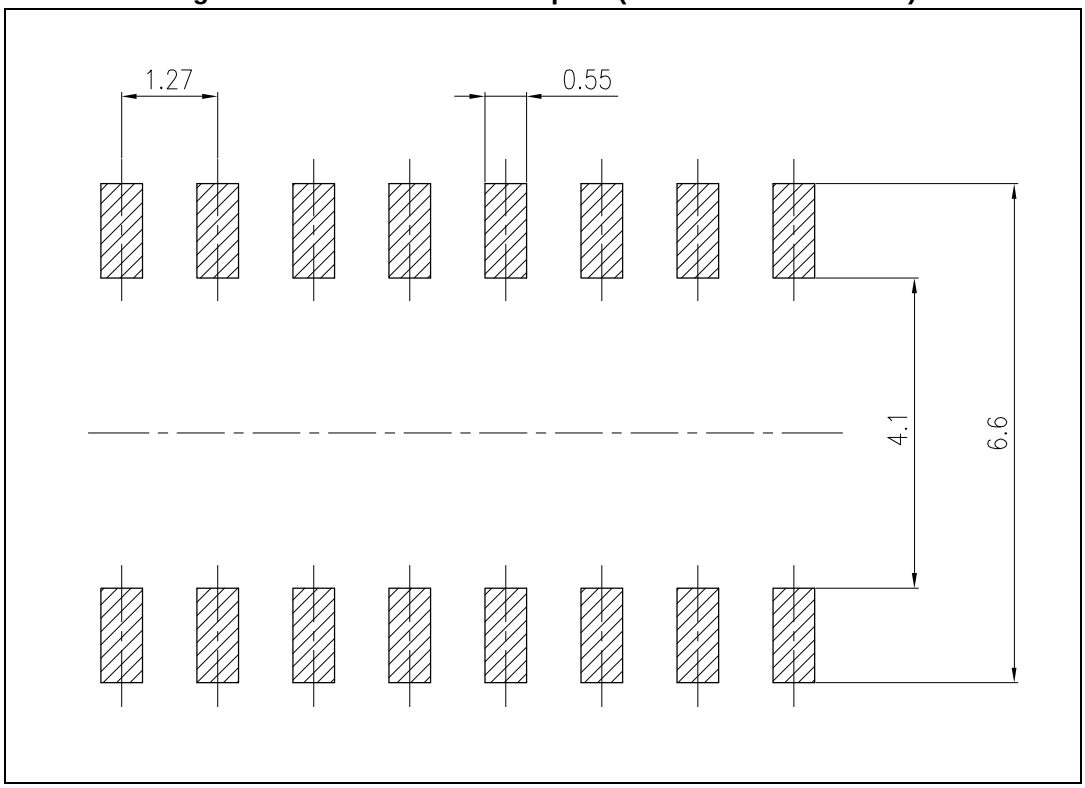


Figure 22. Recommended footprint (dimensions are in mm)

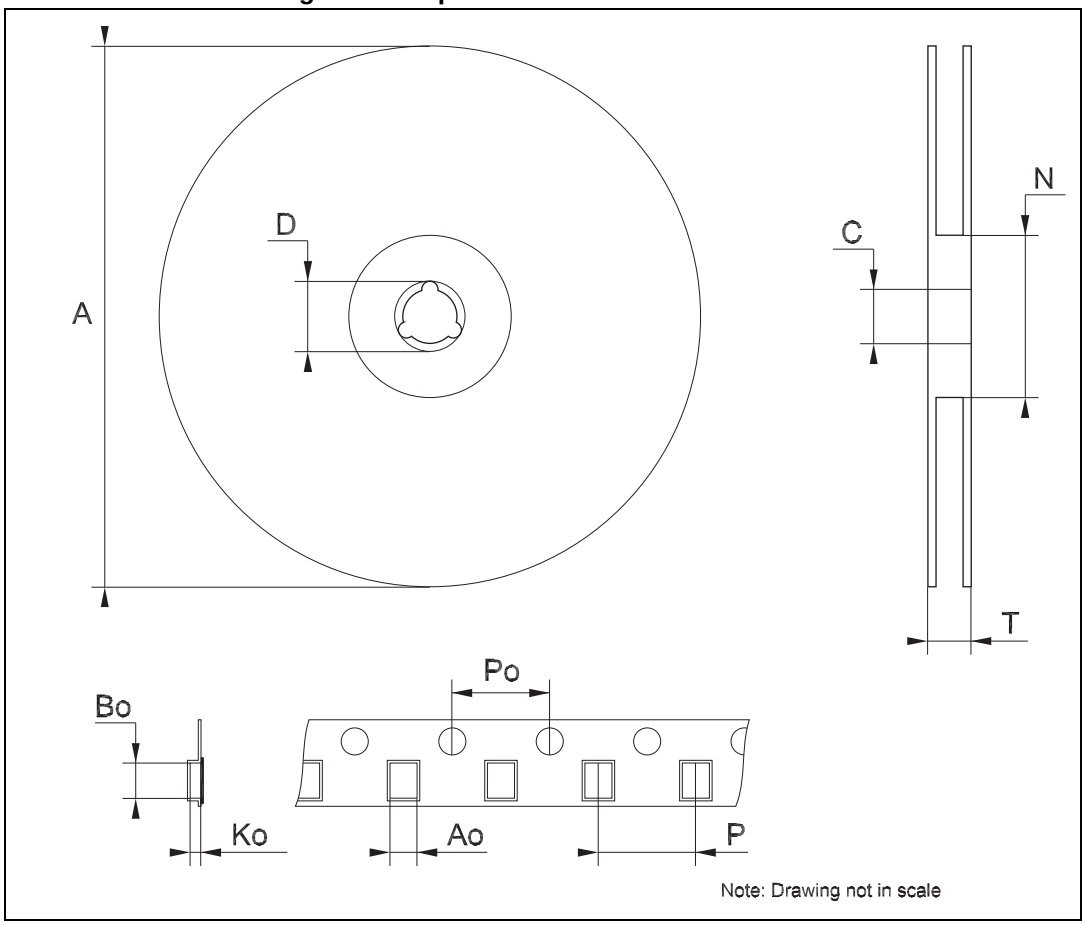


11 Packaging mechanical data

Table 16. HTSSOP16 EP tape and reel mechanical data

Dim	mm		
	Min	Typ	Max
A			330
C	12.8		13.2
D	20.2		
N	60		
T			22.4
Ao	6.7		6.9
Bo	5.3		5.5
Ko	1.6		1.8
Po	3.9		4.1
P	7.9		8.1

Figure 23. Tape and reel for HTSSOP16 EP



12 Revision history

Table 17. Document revision history

Date	Revision	Changes
23-May-2007	1	First release
28-Jun-2007	2	Updated *Table 7 on page 7*
12-Mar-2008	3	Updated *Table 8 on page 8* and added *Figure 11* and *Figure 12 on page 15*
07-Aug-2008	4	Updated *Section 8: Typical characteristics on page 14*
27-Aug-2010	5	Updated *Note: on page 3*
10-Jul-2013	6	Updated *Section 10: Package mechanical data*, *Figure 3: OE terminal* and *Figure 4: LE terminal*. Added *Section 11: Packaging mechanical data*.

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